





(1.27 mm) .050"

**CLP SERIES** 

# PROFILE DUAL WIPE SOCKET

#### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

#### Insulator Material:

Black Liquid Crystal Polymer Contact Material: Phosphor Bronze

Plating: Sn or Au over 50 μ" (1.27 μm) Ni

Current Rating (CLP/FTSH): 3.3 A per pin

(1 pin powered per row) Voltage Rating: 240 VAC/340 VDC

#### **Operating Temp Range:** 55 °C to +125 °C

Contact Resistance:  $10~\text{m}\Omega$ 

#### Insertion Depth:

Top Entry = (1.40 mm) .055" minimum, Bottom Entry = (2.41 mm) .095" minimum plus board thickness DH Entry = (2.31 mm) .091" to (2.67 mm) .105"

Normal Force: 60 grams (0.59 N) average

Max Cycles: 100 with 10 μ" (0.25 μm) Au RoHS Compliant:

## **PROCESSING**

# Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (02-35) (0.15 mm) .006" max (36-50)

#### RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



### **ALSO AVAILABLE** (MOQ Required)

- · Single row
- · Other platings

Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.



